

AMENDMENTS TO THE CLAIMS:

Please cancel Claims 16 and 23 without prejudice to or disclaimer of the subject matter recited therein.

Please amend Claims 15 and 22 as follows:

1-14. (Canceled)

15. (Currently Amended) An exposure apparatus for aligning a substrate and performing exposure using the aligned substrate, said apparatus comprising:

a first alignment system, having a first stage and a first image sensing unit, to detect a position of a first mark on the substrate on said first stage using said first image sensing unit;

a transfer system to transfer the substrate, on which the position of the first mark has been detected by said first alignment system, from said first stage onto a second stage; and

a second alignment system, having said second stage and a second image sensing unit of which magnification is higher than that of said first image sensing unit, to detect a position of a second mark on the substrate on said second stage using said second image sensing unit, and to align the substrate based on the detection obtained by using said second image sensing unit,

wherein said first and second alignment systems and said transfer system are arranged such that the second mark on the substrate transferred on said second stage is positioned within a view of said second image sensing unit, and
wherein the first mark and the second mark are the same.

16. (Canceled)

17. (Previously Presented) An apparatus according to claim 15, wherein said first alignment system aligns the substrate based on the detection obtained by using said first image sensing unit.

18. (Previously Presented) An apparatus according to claim 15, wherein the second mark is positioned within the view by moving said second stage based on the detection obtained by using said first image sensing unit.

19. (Previously Presented) An apparatus according to claim 15, wherein said first alignment system detects the position of the first mark on the substrate aligned based on an outer shape of the substrate.

20. (Previously Presented) An apparatus according to claim 17, wherein said first alignment system drives said first stage so as to bring the first mark to a reference position.

21. (Previously Presented) An apparatus according to claim 19, wherein said first alignment system comprises a member onto which an end face of the substrate is pressed.

22. (Currently Amended) An alignment method of aligning a substrate, said method adapted to an exposure apparatus for performing exposure using the aligned substrate, said method comprising:

a first alignment step of detecting a position of a first mark on the substrate on a first stage using a first image sensing unit;

a transfer step of transferring the substrate, on which the position of the first mark has been detected in said first alignment step, from the first stage onto a second stage; and

a second alignment step of detecting a position of a second mark on the substrate on the second stage using a second image sensing unit of which magnification is higher than that of the first image sensing unit, and of aligning the substrate based on the detection obtained by using the second image sensing unit,

wherein the second mark on the substrate on the second stage is positioned within a view of the second image sensing unit through said first alignment step and said transfer step, and

wherein the first mark and the second mark are the same.

23. (Canceled)

24. (Previously Presented) A method according to claim 22, wherein the substrate is aligned based on the detection obtained by using the first image sensing unit, in said first alignment step.

25. (Previously Presented) A method according to claim 22, wherein the second mark is positioned within the view by moving the second stage based on the detection obtained by using the first image sensing unit.

26. (Previously Presented) A method according to claim 22, wherein the position of the first mark on the substrate, aligned based on an outer shape of the substrate, is detected in said first alignment step.

27. (Previously Presented) A method according to claim 24, wherein the first stage is driven so as to bring the first mark to a reference position in said first alignment step.

28. (Previously Presented) A method according to claim 26, wherein the substrate is aligned by pressing an end face of the substrate onto a member in said first alignment step.